			D D	m
L Number		Search Text	DB	Time stamp
-		bond\$4 and stack and packag\$4	USPAT	2002/06/05 10:35 2002/10/22 12:17
_	1383		USPAT	2002/10/22 12:1/
	201	wire	TICDAM	2003/05/21 14:13
_	291	•	USPAT	2003/03/21 14:13
	2.2	stack TC came stack\$4 came bump\$2 and vertical	USPAT	2002/10/25 07:45
-		IC same stack\$4 same bump\$2 and vertical	USPAT	2002/10/25 07:45
	221	(IC or substrate\$2 or chip) same stack\$4 same bump\$2 and vertical	USTAI	2002/10/25 00.14
	1105	((257/686) or (438/455)).CCLS.	USPAT	2002/10/25 08:15
-	395	(((257/686) or (438/455)).CCLS.) & stack	USPAT	2002/10/25 08:46
-		("6329594").PN.	USPAT	2002/10/25 08:46
_		("4266282" "5019943" "5227664"	USPAT	2002/10/25 08:55
_	11	"5347428" "5432729" "5793116"	ODIMI	2002/10/23 00:33
		"5892179" "5963793" "5990472"		
		"6134120" "6169325").PN.		
_	26	5327327.URPN.	USPAT	2002/10/25 08:56
_		("4525921" "4617160" "4646128"	USPAT	2002/10/25 08:57
	9	"4704319" "4706166" "4764846"	ODIFII	2002/10/23 00:3/
		"4983533" "5025306" "5104820").PN.		
	6	5561593.URPN.	USPAT	2002/10/25 08:58
_	_	("3193789" "4338621" "4525921"	USPAT	2002/10/25 08:58
_	21	"4551629" "4617160" "4646128"	ODIM	2002/10/29 00:30
		"4672737" "4706166" "4727410"		
		"5015858" "5072331" "5075238"		
		"5092036" "5096426" "5104820"		
		"5111050" "5129142" "5135606"		
		"5309318" "5374196" "5426566").PN.		
	٥	5952725.URPN.	USPAT	2002/10/25 08:58
_		("4264917" "4472875" "4826787"	USPAT	2002/10/25 08:59
_	30	"4862245" "5012323" "5019943"	USIAI	2002/10/23 00:33
		"5051865" "5104820" "5146308"		
		"5147815" "5229647" "5239198"		
		"5252857" "5266833" "5291061"		
		"5323060" "5331235" "5399898"		
		"5422435" ["5426072" "5432681"		
		"5438224" "5466634" "5471369"		
		"5483024" "5484959" "5495398"		
		"5547906" "5567654" "5675180").PN.		
_	8	("4868712" "4894706" "5434745"	USPAT	2002/10/25 09:00
	•	"5611876" "5708297" "5726492"	001111	2002, 10, 23 03.00
		"5786628" "5923080").PN.		
<u> </u>	Λ	6380616.URPN.	USPAT	2003/05/21 15:17
_		substrate\$1 same bump\$2 and stack	USPAT	2003/05/21 14:13
_	21	• .	USPAT	2003/05/21 14:17
	2- 1	kerf\$		
_	348	substrate\$1 same bump\$2 near5 extend\$	USPAT	2003/05/21 14:18
_	27	("3501681" "3663184" "3760238"	USPAT	2003/05/21 16:10
		"3770874" "3871014" "3942187"	· · · ·	
		"4074342" "4113578" "4855809"		
		"4948754" "4950623" "4962058"		
		"5113314" "5160409" "5162257"		
		"5194137" "5250843" "5293006"		
		"5327013" "5327327" "5347428"		
		"5354711" "5406701" "5424920"		
		"5432729" "5453582" "5616962").PN.		
_	10	5793116.URPN.	USPAT	2003/05/21 14:25
_	417		USPAT	2003/05/21 16:11
_	348	* *	USPAT	2003/05/21 16:11
		semiconductor		
_	654	solder adj bump\$ near5 ball\$1 and	USPAT	2003/05/21 16:12
		semiconductor		
=	797	solder adj bump\$ near5 ball\$1	USPAT	2003/05/21 16:12
		near10semiconductor		
_	93	· · · · · · · · · · · · · · · · · · ·	USPAT	2003/05/21 16:12
		semiconductor		